

On page 44, line 9, amend "85" to --854--;

On page 46, line 15, amend "7-7" to --21-21--;

On page 76, line 24, insert --, which-- after "615"; and

On page 78, line 7, amend "thee" to --the--.

IN THE CLAIMS:

Please cancel claims 15 and 18, and amend claims 1-14, 16 and 17, as follows:

1. (Amended) A [semiconductor] microelectronic workpiece holder for use in a [semiconductor] microelectronic electroplating apparatus used to plate a metal or metals onto a [semiconductor] microelectronic workpiece, comprising:

a workpiece support mounted to support a [semiconductor] microelectronic workpiece in position with at least a processed surface of the workpiece being in contact with a plating bath;

at least one electrode [finger] which is electrically conductive and capable of receiving and conducting electrical current supplied thereto;

19/ said at least one electrode [finger] having a contact face forming part thereof which is adapted to engage a surface of the [semiconductor] microelectronic workpiece to conduct electrical current [between] therebetween;

wherein said contact face is pre-conditioned by plating onto said contact face a contact face plating layer made from a metal-containing contact face plating material which comprises the same principal metal or metals being [is similar to a workpiece plating material which is to be] plated onto the [semiconductor] microelectronic workpiece.

2. (Amended) A [semiconductor] microelectronic workpiece holder [according to] as claimed in claim 1 wherein said contact face plating layer is at least 0.1 microns in thickness.